

# Vibration Isolation System

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LCGT  
2<sup>nd</sup> f2f meeting  
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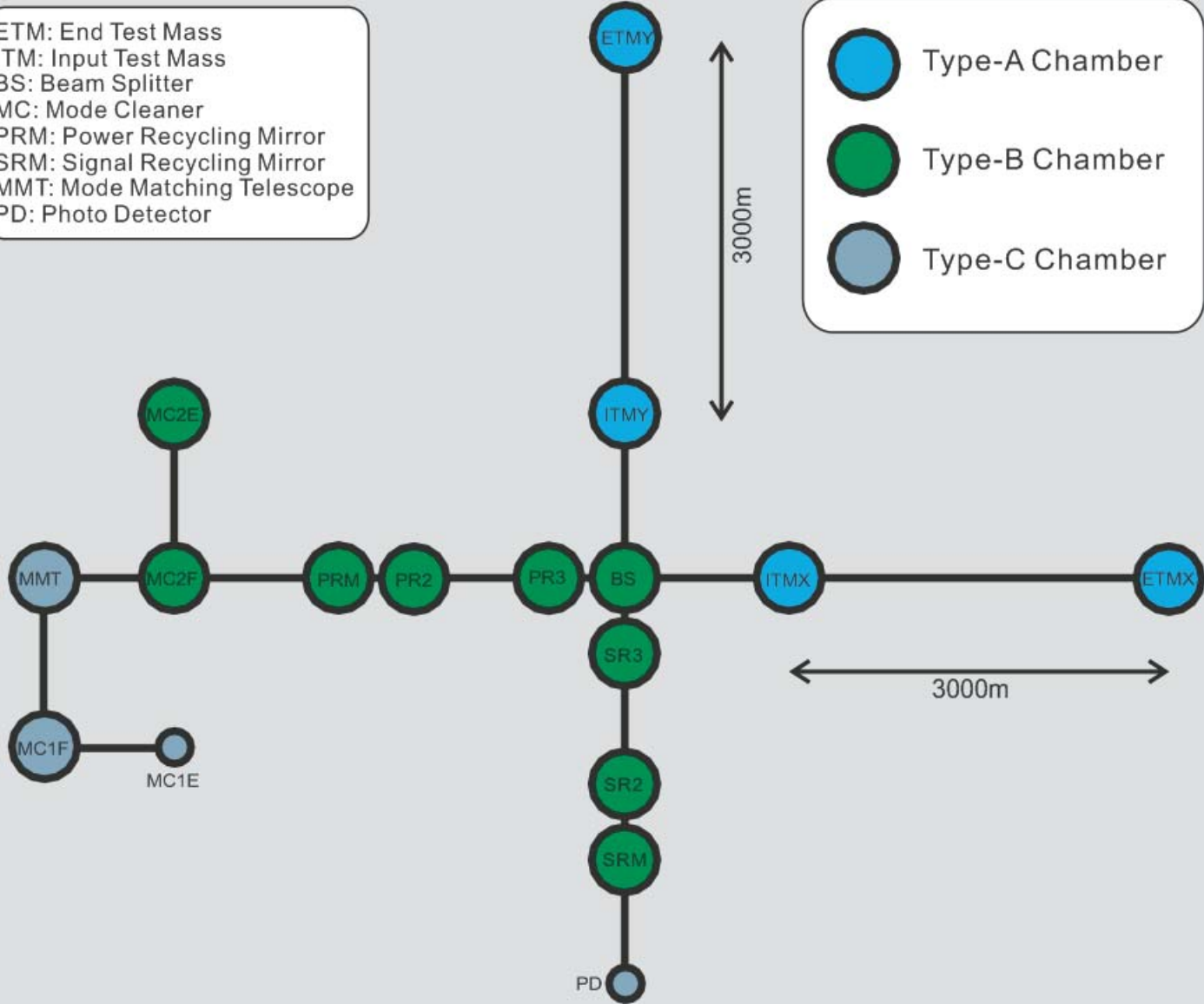
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# 1. Configuration

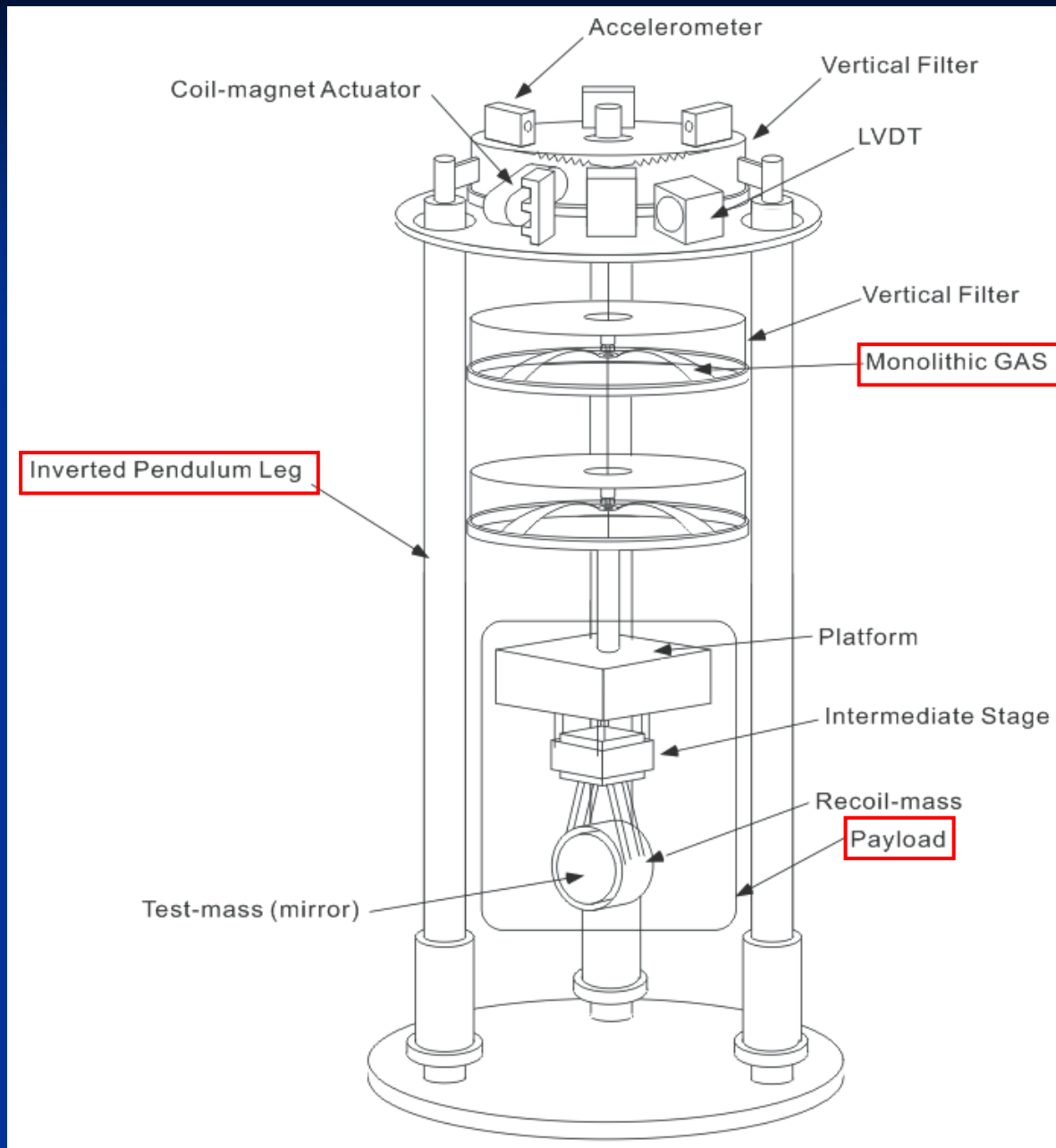
# 1-a. Location

ETM: End Test Mass  
ITM: Input Test Mass  
BS: Beam Splitter  
MC: Mode Cleaner  
PRM: Power Recycling Mirror  
SRM: Signal Recycling Mirror  
MMT: Mode Matching Telescope  
PD: Photo Detector

- Type-A Chamber
- Type-B Chamber
- Type-C Chamber



# 1-b. Structure



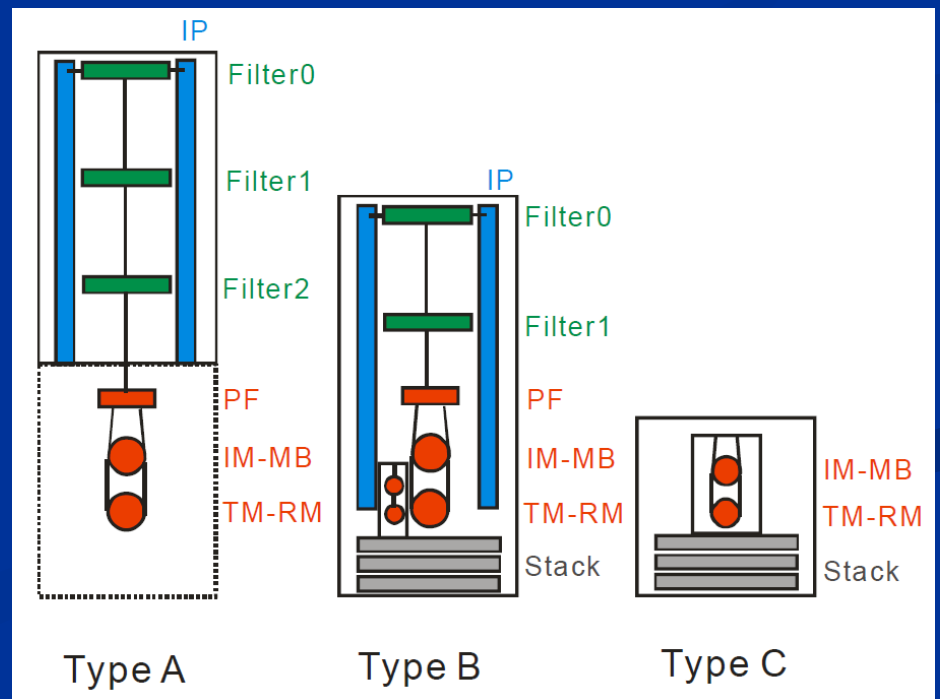
# 1-c. Configuration

## ■ Vacuum chamber

- A)  $\phi 2\text{m} \times (2.5\text{m} + 2.45\text{m cryostat})$
- B)  $\phi 2\text{m} \times 4.3\text{m}$
- C)  $\phi 1\text{-}2\text{m} \times 3\text{m}$

## ■ Vibration Isolation System

- A) IP + GASF (3 stage) + Payload (cryogenic)
- B) IP + GASF (2 stage) + Payload (room temp.)
- C) STACK + Double-pendulum



## 1-c. Configuration (Plan A)

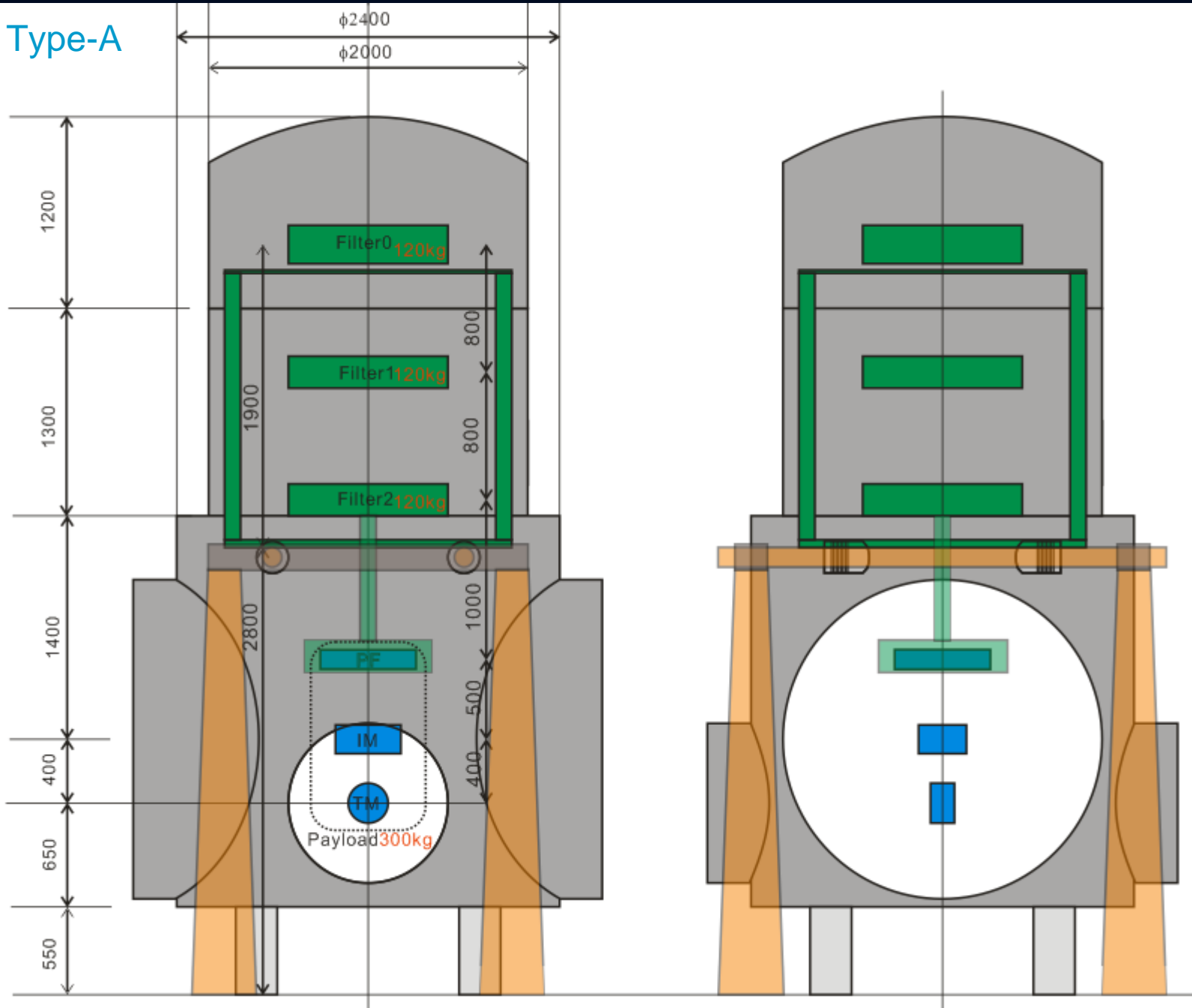
	iLCGT	bLCGT
ITMX, ITMY, ETMX, ETMY	Type-A IP-GASF <sup>(fixed)</sup> + Type-B Payload	Type-A SAS
BS, PR2, PR3, SR2, SR3, MC2F, MC2E	Stack + Type-B Payload	Type-B SAS
PRM, SRM	none	Type-B SAS
MC1F, MC1E	none	Type-C
MMT, PD	Type-C	Type-C

## 1-c. Configuration (Plan B)

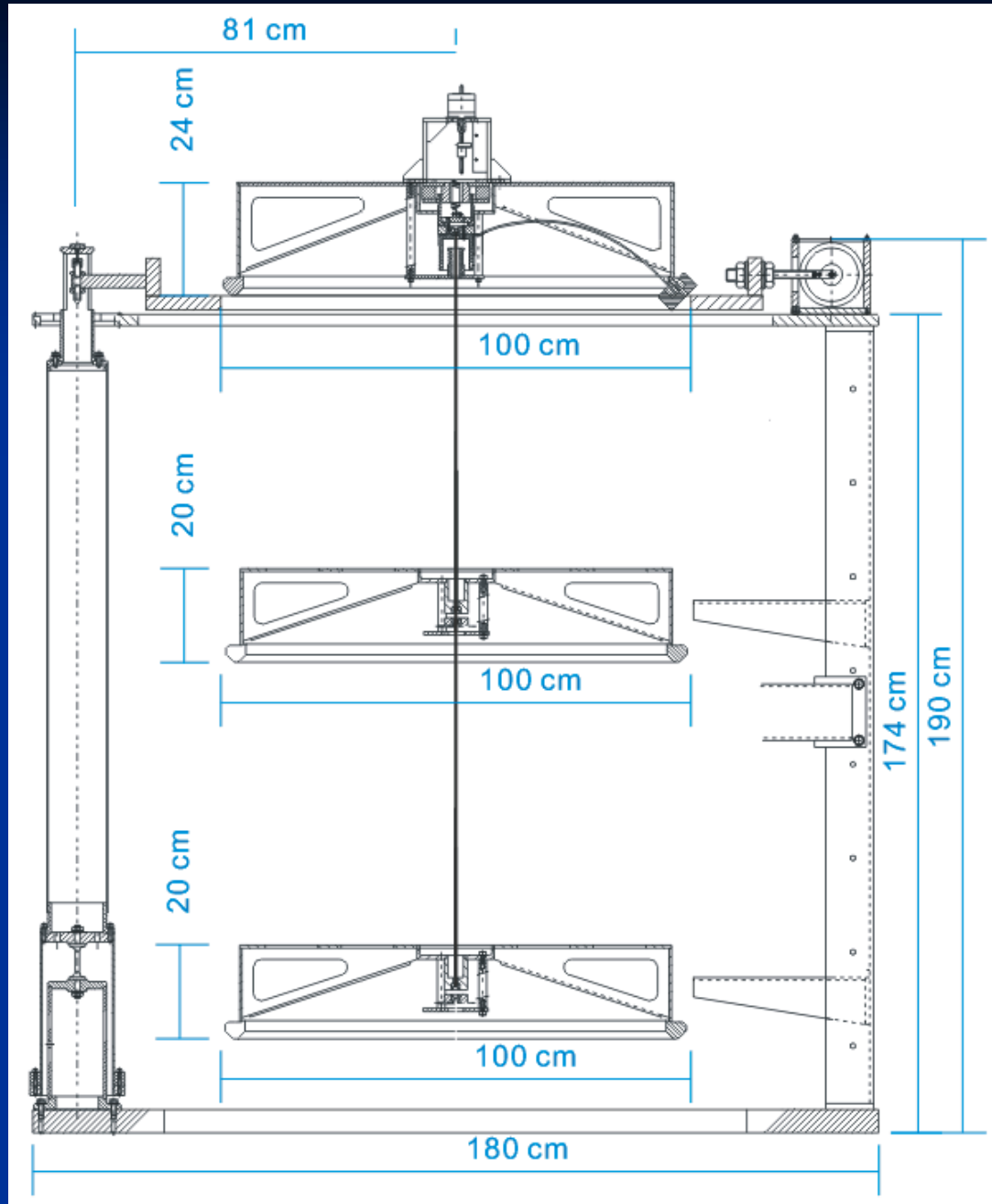
	iLCGT	bLCGT
ITMX, ITMY, ETMX, ETMY	Type-A IP-GASF <sup>(Fixed)</sup> + Type-A Payload	Type-A SAS
BS, PR3, SR3	Stack + Type-A Payload	Type-B IP-GASF + Type-A Payload
PRM, SRM, MC1F, MC1E	none	Type-C
PR2, SR2, MC2F, MC2E, MMT, PD	Type-C	Type-C



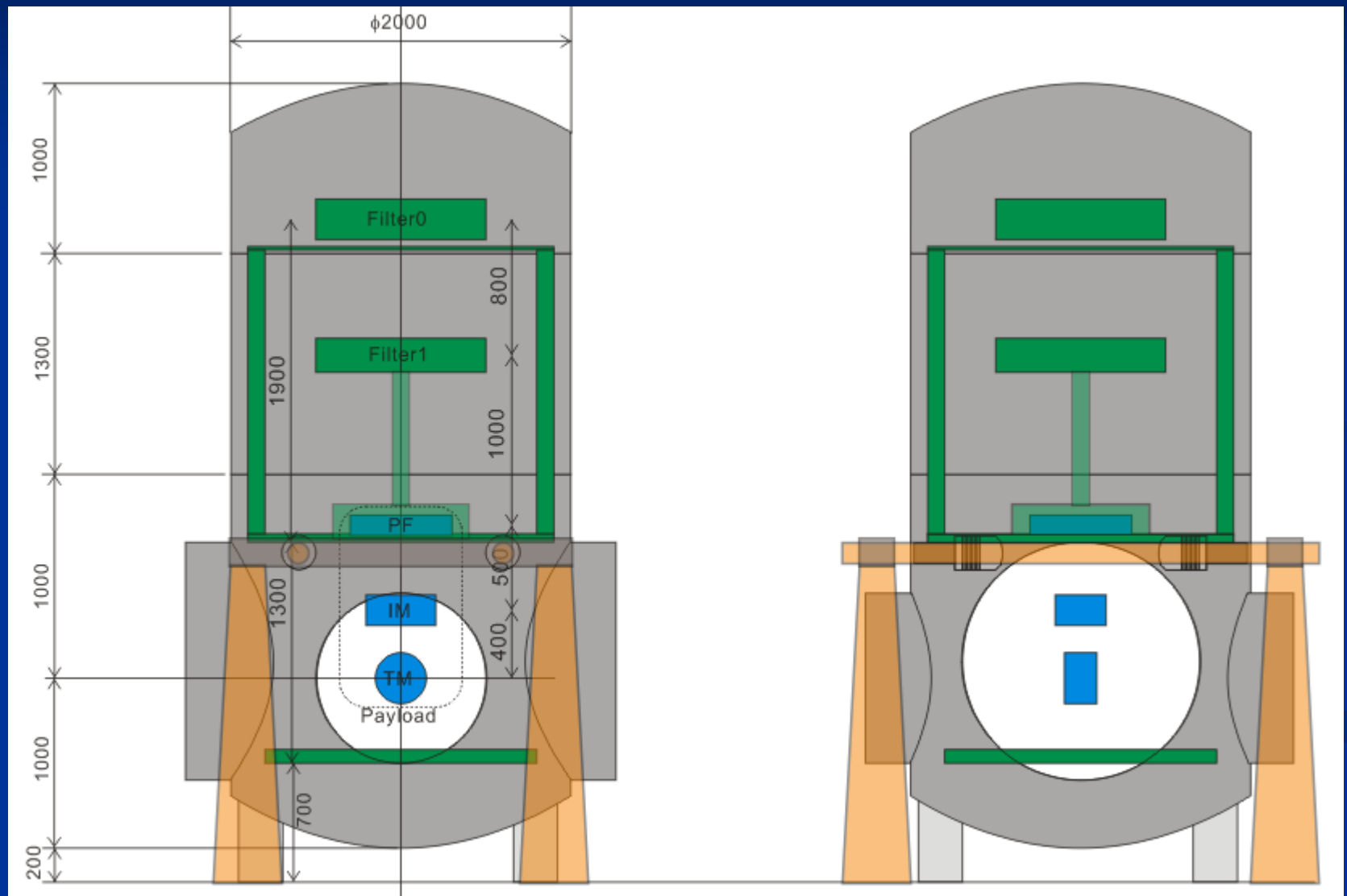
# Type-A



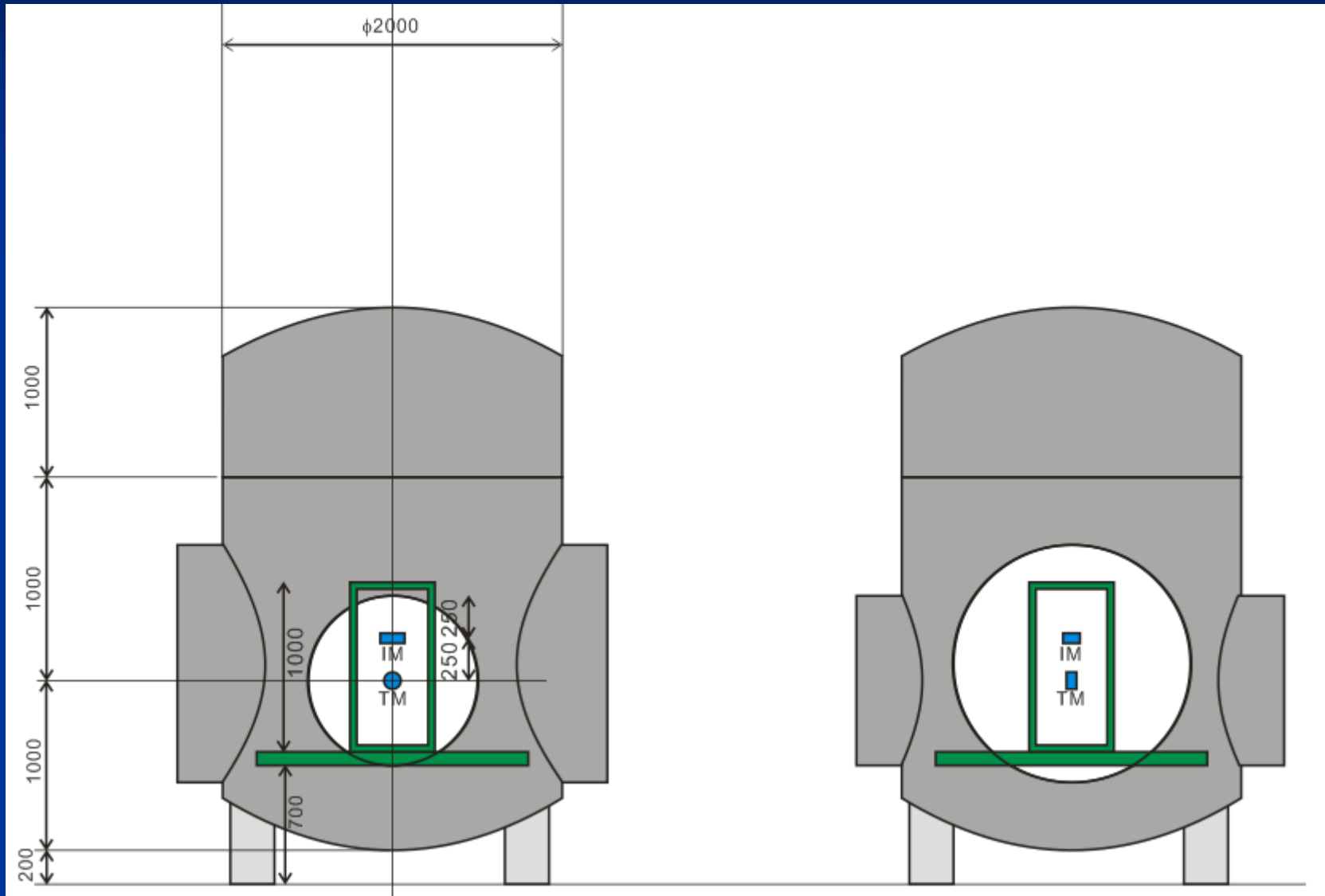
# Type-A



# Type-B



# Type-C



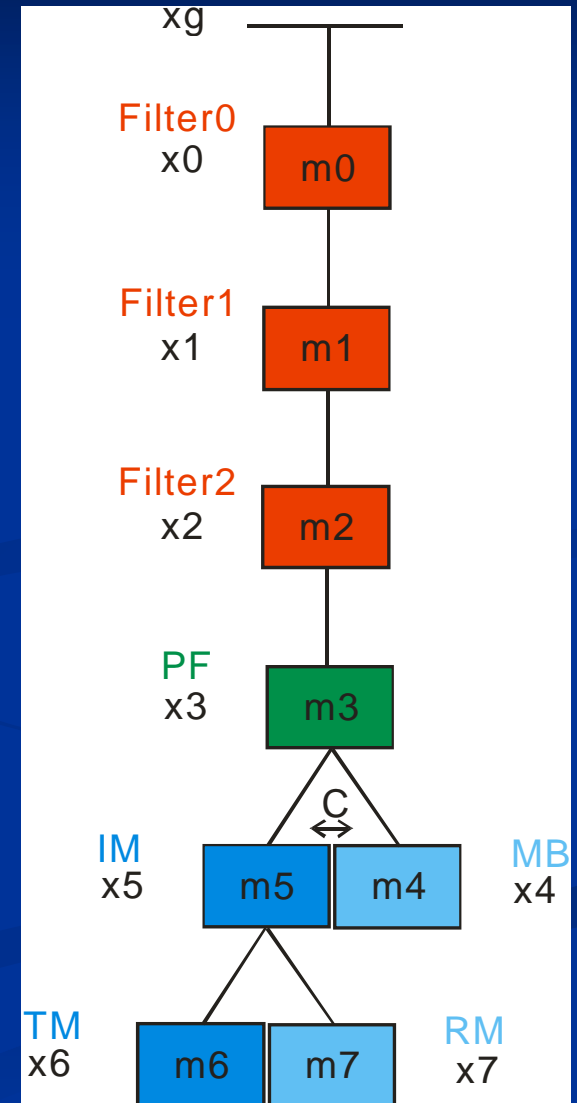
## 2. Performance

## 2-a. Modeling

### Type-A

- Equation of motion of 8 material points model
- **8x8** stiffness matrix
- Refer parameters of TAMA-SAS
- Calculated by MATLAB

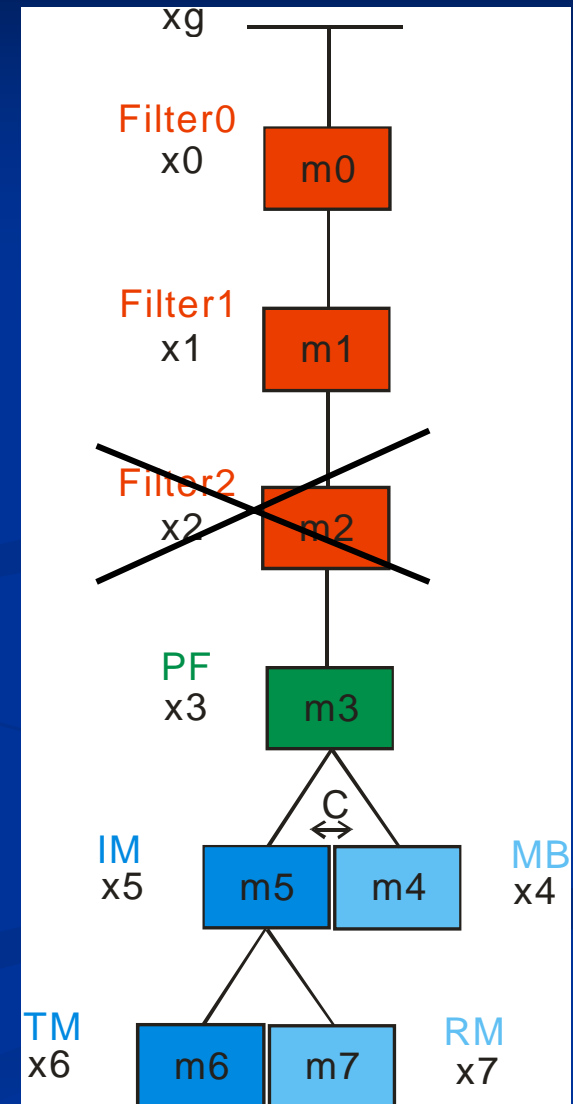
	m	Q	f0	C
	[kg]		[Hz]	[kg·Hz]
Filter0	120	1	0.07	-
Filter1	120	100	0.56	-
Filter2	120	100	0.56	
PF	120	100	0.5	-
IM	60	1000	0.7	530
MB	60	1000	0.7	530
TM	30	1000	0.8	-
RM	30	6	0.8	-



## Type-B

- Equation of motion of 7 material points model
- $7 \times 7$  stiffness matrix
- Masses are about a half of Type-A's
- Calculated by MATLAB

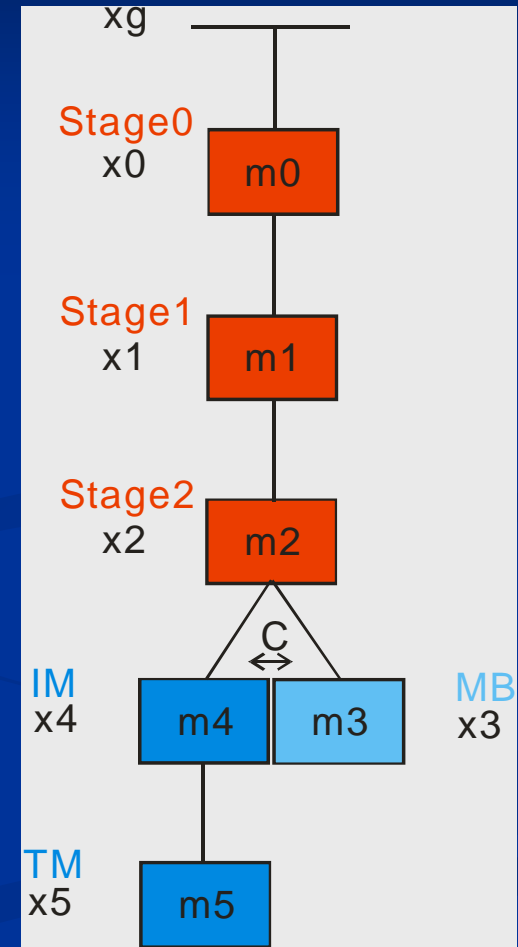
	m	Q	f0	C
	[kg]		[Hz]	[kg·Hz]
Filter0	60	1	0.07	-
Filter1	60	100	0.56	-
PF	60	100	0.5	-
IM	30	1000	0.7	265
MB	30	1000	0.7	265
TM	16	1000	0.8	-
RM	16	6	0.8	-



## Type-C

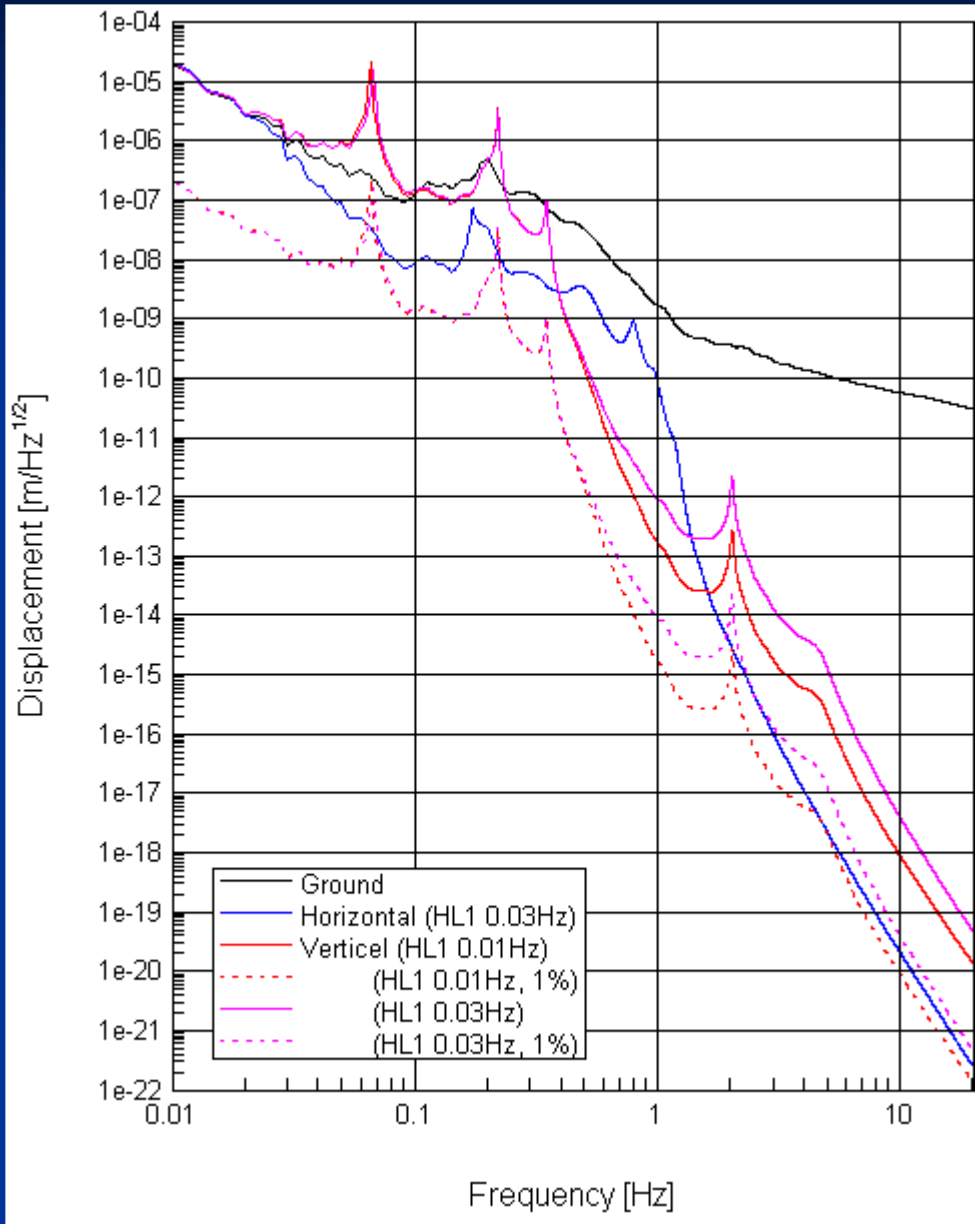
- Equation of motion of 6 material points model
- **6x6** stiffness matrix
- Model for Stack is simplified
- Calculated by MATLAB

	m	Q	f0	C
	[kg]		[Hz]	[kg·Hz]
Stage0	200	3	5	-
Stage1	200	3	4.5	-
Stage2	200	3	4	-
IM	1	1000	1	12.5
MB	1	1000	3	12.5
TM	1	1000	1	-



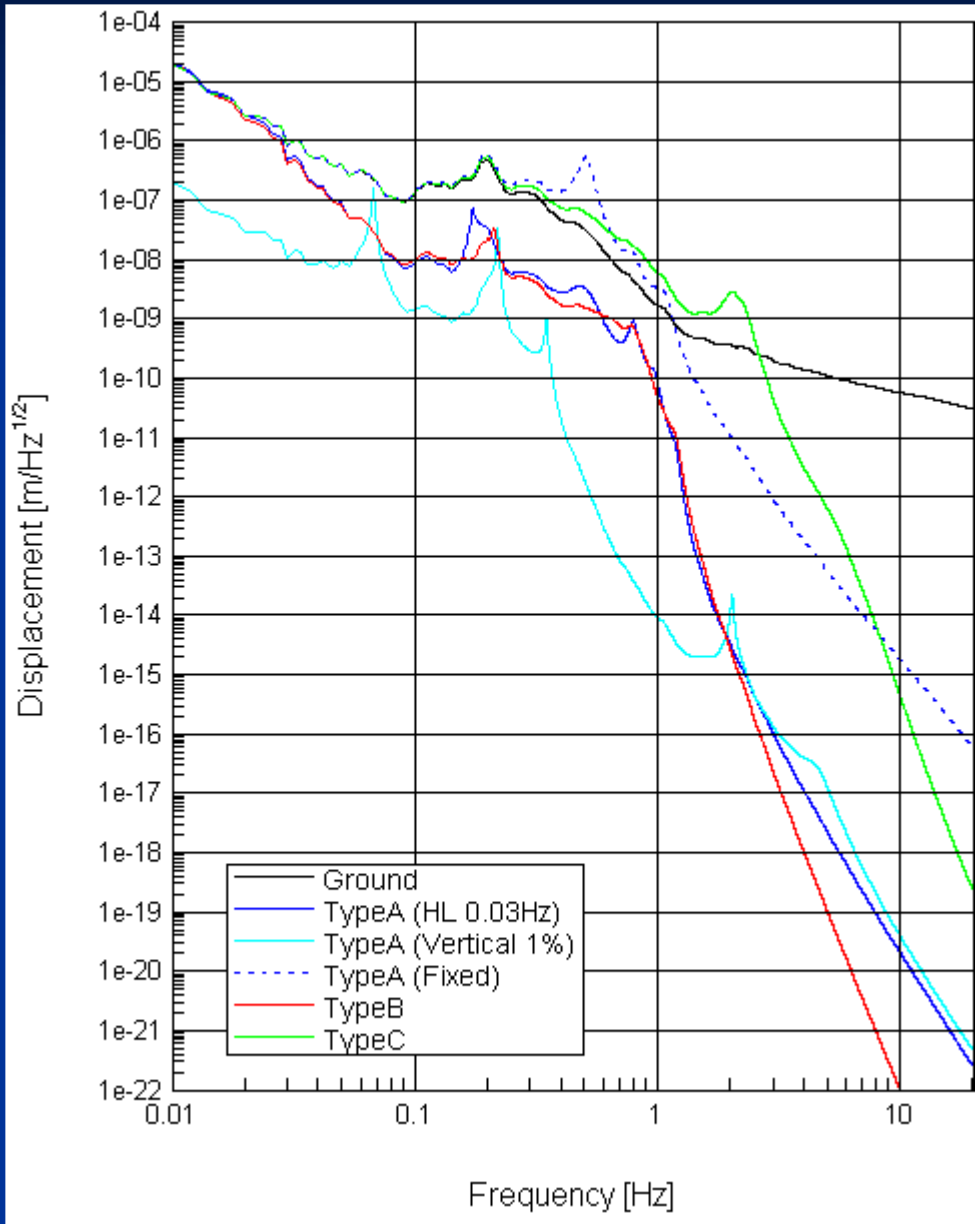


## 2-b. Displacement of test mass



- The vertical isolation is better than the horizontal isolation around 1 Hz because of 3 stage GAS filters.
- Since the final stage (TM) is suspended by 4 sapphire fibers of  $\phi$  1.8mm, the vertical resonant frequency is about 100Hz.
- Heat links of 0.01Hz with 1% coupling from vertical mode satisfy demands at 5Hz. Heat links of 0.03Hz is NG but practically OK.

## 2-c. Displacement of each system



- The isolation of Type-B is better than the isolation of Type-A with heat links.
- When the part of IP-GASF of Type-A is fixed (iLCGT), the isolation of Type-A is worse than the isolation of Type-C with stack.

## 2-d. RMS

			Type-A	Type-B	Type-C
Microseisms	normal	[ $\mu$ m]	1.0 (0.006)	1.0 (0.006)	1.0 (0.1)
		[ $\mu$ m/s]	0.08 (0.008)	0.08 (0.008)	0.2 (0.2)
	large	[ $\mu$ m]	0.7 (0.10)	0.7 (0.09)	2.0 (1.9)
		[ $\mu$ m/s]	0.12 (0.11)	0.11 (0.10)	2.3 (2.3)

Integration 0.01-4Hz  
(Integration 0.1-4Hz)

Type-A,B vs. C

0.1  $\rightarrow$  2 [ $\mu$ m] x20

0.1  $\rightarrow$  2 [ $\mu$ m/s] x20

## 3. Control

## 3-a. Sensor and actuator

	Filter0	Filter1	Filter2	PF	IM-MB	TM-RM
Sensor	ACC(H) x3 ACC(V) x1 LVDT(H) x3 LVDT(V) x1	LVDT(V) x1	LVDT(V) x1 OL x1	PS(H) x3 PS(V) x3 OL x1	PS(H) x3 PS(V) x3	PS(H) x1 PS(V) x1 OL x1
Actuator	MC(H) x3 MC(V) x1		MC(Y) x1	MC(H) x3 MC(V) x3	MC(H) x3 MC(V) x3	MC(H) x2 MC(V) x2
Motor	STEP(H) x3 STEP(V) x1		PICO(Y) x1	STEP(H) x2 STEP(V) x2		

ACC: accelerometer, LVDT: linear variable differential transformer PS: position sensor, OL: optical lever, MC: magnet-coil, STEP: stepping motor, PICO: picomotor

### For cryogenic

Stepping motor: tested in Rome, 4.8K ok!

Position sensor: shadow sensor → fiber sensor

# 4. Schedule

